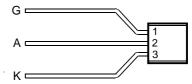
- 2 A Continuous On-State Current
- 15 A Surge-Current
- Glass Passivated Wafer
- 400 V to 600 V Off-State Voltage
- Max I<sub>GT</sub> of 200 μA
- Package Options

PACKAGE	PACKING	PART # SUFFIX		
LP	Bulk	(None)		
LP with fomed leads	Tape and Reel	R		



MDC1AA





MDC1AB

### absolute maximum ratings over operating case temperature (unless otherwise noted)

RATING			VALUE	UNIT	
Panatitiva neek off state valtage (see Note 1)	TICP106D	V	400	V	
Repetitive peak off-state voltage (see Note 1)	TICP106M	$V_{DRM}$	600		
Panatitiva naak rayarsa yaltaga	TICP106D	V	400	W	
Repetitive peak reverse voltage	TICP106M	$V_{RRM}$	600	٧	
Continuous on-state current at (or below) 85°C case temperature (see Note 2)		I <sub>T(RMS)</sub>	2	Α	
Surge on-state current (see Note 3)			15	Α	
Peak positive gate current (pulse width ≤ 300 μs)			0.2	Α	
Average gate power dissipation (see Note 4)			0.3	W	
Operating case temperature range			-40 to +110	°C	
Storage temperature range			-40 to +125	°C	
Lead temperature 3.2 mm from case for 10 seconds		$T_L$	230	°C	

- NOTES: 1. These values apply when the gate-cathode resistance  $R_{GK}$  = 1 k $\Omega$ .
  - 2. These values apply for continuous dc operation with resistive load. Above 85°C derate linearly to zero at 110°C.
  - 3. This value applies for one 50 Hz half-sine-wave when the device is operating at (or below) the rated value of peak reverse voltage and on-state current. Surge may be repeated after the device has returned to original thermal equilibrium.
  - 4. This value applies for a maximum averaging time of 20 ms.



# TICP106 SERIES SILICON CONTROLLED RECTIFIERS

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## electrical characteristics at 25°C case temperature (unless otherwise noted)

	PARAMETER		TEST CONDITI	ONS	MIN	TYP	MAX	UNIT
I <sub>DRM</sub>	Repetitive peak off-state current	V <sub>D</sub> = rated V <sub>DRM</sub>	R <sub>GK</sub> = 1 kΩ				20	μΑ
I <sub>RRM</sub>	Repetitive peak reverse current	$V_R$ = rated $V_{RRM}$	I <sub>G</sub> = 0				200	μΑ
I <sub>GT</sub>	Gate trigger current	V <sub>AA</sub> = 6 V	$R_L = 100 \Omega$	t <sub>p(g)</sub> ≥ 20 μs		60	200	μΑ
V <sub>GT</sub>	Gate trigger voltage	V <sub>AA</sub> = 6 V	$R_L = 100 \Omega$ $R_{GK} = 1 k\Omega$	$t_{p(g)} \ge 20 \; \mu s$	0.4		1	<b>V</b>
I <sub>H</sub>	Holding current	V <sub>AA</sub> = 6 V	$R_{GK} = 1 k\Omega$	Initiating I <sub>T</sub> = 10 mA			5	mA
$V_{TM}$	Peak on-state voltage	I <sub>TM</sub> = 1 A	(see Note 5)				1.5	٧

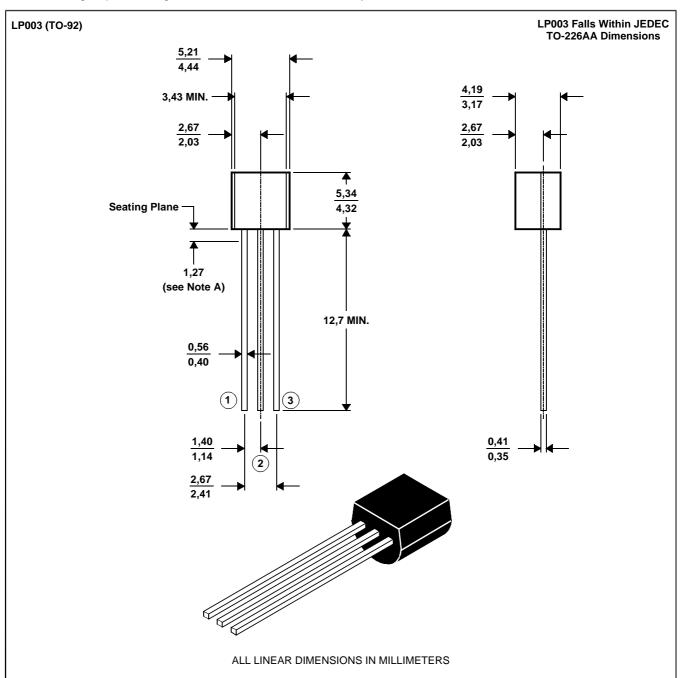
NOTE 5: This parameter must be measured using pulse techniques, t<sub>p</sub> = 1 ms, duty cycle ≤ 2 %. Voltage sensing-contacts, separate from the current carrying contacts, are located within 3.2 mm from the device body.

#### **MECHANICAL DATA**

## LP003 (TO-92)

## 3-pin cylindical plastic package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTE A: Lead dimensions are not controlled in this area.

**MDXXAX** 



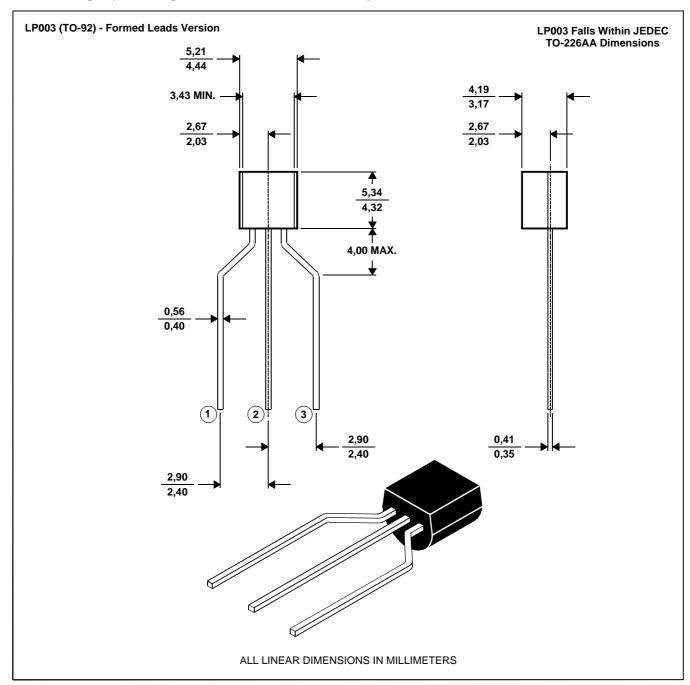
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#### **MECHANICAL DATA**

## LP003 (TO-92)

## 3-pin cylindical plastic package

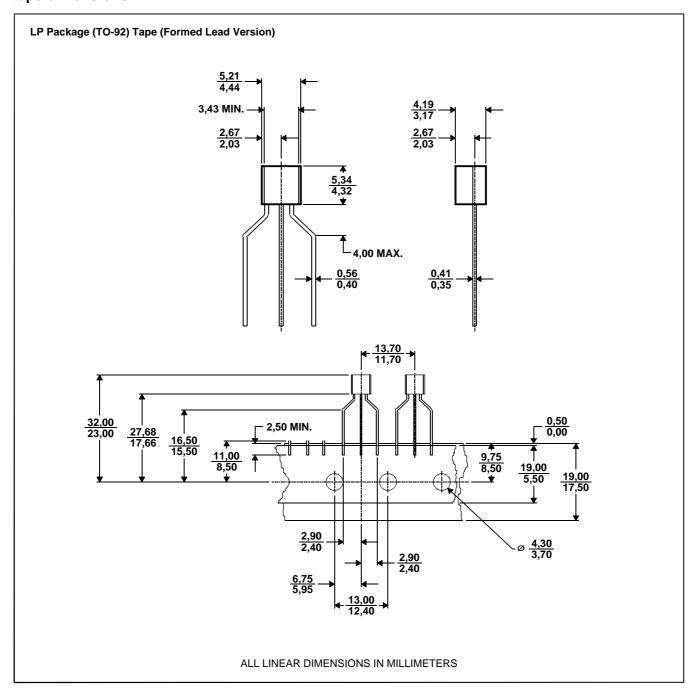
This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



MDXXAR

### **MECHANICAL DATA**

LPR tape dimensions



**MDXXAS** 



## TICP106 SERIES SILICON CONTROLLED RECTIFIERS

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